

Cheng Qian

List of Publications by Year in descending order

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38
papers

652
citations

623188

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25
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40
all docs

40
docs citations

40
times ranked

592
citing authors

#	ARTICLE	IF	CITATIONS
1	Thermal Management on IGBT Power Electronic Devices and Modules. IEEE Access, 2018, 6, 12868-12884.	2.6	181
2	Application of MICMAC, Fuzzy AHP, and Fuzzy TOPSIS for Evaluation of the Maintenance Factors Affecting Sustainable Manufacturing. Energies, 2021, 14, 1436.	1.6	47
3	A novel lifetime prediction for integrated LED lamps by electronic-thermal simulation. Reliability Engineering and System Safety, 2017, 163, 14-21.	5.1	35
4	Effects of Voids on Mechanical and Thermal Properties of the Die Attach Solder Layer Used in High-Power LED Chip-Scale Packages. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1254-1262.	1.4	35
5	Prediction of Lumen Depreciation and Color Shift for Phosphor-Converted White Light-Emitting Diodes Based on A Spectral Power Distribution Analysis Method. IEEE Access, 2017, 5, 24054-24061.	2.6	28
6	Colour shift and mechanism investigation on the PMMA diffuser used in LED-based luminaires. Optical Materials, 2016, 54, 282-287.	1.7	24
7	Application of artificial neural networks for quantitative damage detection in unidirectional composite structures based on Lamb waves. Advances in Mechanical Engineering, 2020, 12, 168781402091473.	0.8	24
8	Color Shift Failure Prediction for Phosphor-Converted White LEDs by Modeling Features of Spectral Power Distribution with a Nonlinear Filter Approach. Materials, 2017, 10, 819.	1.3	22
9	Thermal/luminescence characterization and degradation mechanism analysis on phosphor-converted white LED chip scale packages. Microelectronics Reliability, 2017, 74, 179-185.	0.9	21
10	Optimal Design of Life Testing for High-Brightness White LEDs Using the Six Sigma DMAIC Approach. IEEE Transactions on Device and Materials Reliability, 2015, 15, 576-587.	1.5	20
11	An Alternative Lifetime Model for White Light Emitting Diodes under Thermal and Electrical Stresses. Materials, 2018, 11, 817.	1.3	19
12	Investigation of Step-Stress Accelerated Degradation Test Strategy for Ultraviolet Light Emitting Diodes. Materials, 2019, 12, 3119.	1.3	17
13	Reliability Assessment of Light-Emitting Diode Packages With Both Luminous Flux Response Surface Model and Spectral Power Distribution Method. IEEE Access, 2019, 7, 68495-68502.	2.6	17
14	Characterization and reconstruction for stochastically distributed void morphology in nano-silver sintered joints. Materials and Design, 2020, 196, 109079.	3.3	16
15	Numerical Thermal Analysis and Optimization of Multi-Chip LED Module Using Response Surface Methodology and Genetic Algorithm. IEEE Access, 2017, 5, 16459-16468.	2.6	15
16	Phosphor-silicone interaction effects in high power white light emitting diode packages. Journal of Materials Science: Materials in Electronics, 2017, 28, 17557-17569.	1.1	14
17	Machine-Learning Assisted Prediction of Spectral Power Distribution for Full-Spectrum White Light-Emitting Diode. IEEE Photonics Journal, 2020, 12, 1-18.	1.0	14
18	A Gamma Process-Based Prognostics Method for CCT Shift of High-Power White LEDs. IEEE Transactions on Electron Devices, 2018, 65, 2909-2916.	1.6	13

#	ARTICLE	IF	CITATIONS
19	Photometric and Colorimetric Assessment of LED Chip Scale Packages by Using a Step-Stress Accelerated Degradation Test (SSADT) Method. <i>Materials</i> , 2017, 10, 1181.	1.3	12
20	Experimental Investigation on the Sintering Kinetics of Nanosilver Particles Used in High-Power Electronic Packaging. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020, 10, 1101-1109.	1.4	12
21	Thermal, optical and electrical analysis on phosphor-converted white LED Chip Scale Packages with both experiment and simulation. , 2016, , .		11
22	Tensile characterization and constitutive modeling of sintered nano-silver particles over a range of strain rates and temperatures. <i>Microelectronics Reliability</i> , 2022, 132, 114536.	0.9	8
23	High Temperature Performance Evaluation and Life Prediction for Titanium Modified Silicone Used in Light-Emitting Diodes Chip Scale Packages. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2020, 142, .	1.2	7
24	Analysis of photoluminescence mechanisms and thermal quenching effects for multicolor phosphor films used in high color rendering white LEDs. , 2016, , .		6
25	Studies of the light output properties for a GaN based blue LED using an electro-optical simulation method. <i>Microelectronics Reliability</i> , 2017, 74, 173-178.	0.9	6
26	Investigation of photoluminescence and thermal effect of phosphor films used in phosphor-converted white LEDs. , 2015, , .		5
27	A design and qualification of LED flip Chip-on-Board module with tunable color temperatures. <i>Microelectronics Reliability</i> , 2018, 84, 140-148.	0.9	5
28	Online prognostication of remaining useful life for random discharge lithium-ion batteries using a gamma process model. , 2019, , .		3
29	A Heuristic Hybrid Optimization Approach for Spare Parts and Maintenance Workers Under Partial Pooling. <i>IEEE Access</i> , 2019, 7, 137835-137847.	2.6	3
30	An Archimedean Copula Function-Based Prediction Method for High-Power White LED Considering Multi-Performance. <i>IEEE Transactions on Electron Devices</i> , 2019, 66, 3405-3410.	1.6	3
31	Characterization of Stochastically Distributed Voids in Sintered Nano-Silver Joints. , 2019, , .		2
32	A New Method for Computing Survival Signature Based on Extended Universal Generating Function. , 2019, , .		2
33	An Electric Fence-Based Intelligent Scheduling Method for Rebalancing Dockless Bike Sharing Systems. <i>Applied Sciences (Switzerland)</i> , 2022, 12, 5031.	1.3	2
34	Study of ultraviolet assisted cure mechanism of the phosphor/silicone composites used in White LEDs. , 2018, , .		1
35	Reliability Analysis of Printed Circuit Boards Based on a Physics of Failure Simulation Method. , 2020, , .		1
36	Study on layout optimization of multi-chip LED modules based on discrete element method. , 2018, , .		0

#	ARTICLE	IF	CITATIONS
37	Reliability Analysis of Critical Systems in A Fuel Booster Pump Using Advanced Simulation Techniques. Materials, 2022, 15, 1989.	1.3	0
38	Semantic Learning and Understanding of multivehicle interaction patterns Using Primitive Driving Patterns With Bayesian Nonparametric Approaches. , 2021, , .		0